

03-19-2004



FORM PTO-1595

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PATENTS ONLY

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

- 3-10-04
1. Name of conveying party(ies):
Masahiro SUNOHARA Kei MURAYAMA Mitsutoshi HIGASHI
 2. Name and Address of receiving party(ies):
SHINKO ELECTRIC INDUSTRIES CO., LTD.
80 Oshimada-machi
Nagano-shi, Nagano 381-2287 Japan
 3. Nature of conveyance:
☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other: _____
 Execution Date(s): February 25, 2004
 4. Application number(s) or patent number(s):
☒ This document is being filed together with a new application:
 (a) The execution date(s) of the application is/are: February 25, 2004
 (b) The title is: METHOD OF PRODUCTION OF MULTILAYER CIRCUIT BOARD WITH BUILT-IN SEMICONDUCTOR CHIP
 OR
☐ This document is being filed after filing of the application:
 (a) Patent Application No(s). /, filed _____; or
 (b) Patent No(s). _____, issued _____
 5. Name and address of party to whom correspondence concerning document should be mailed:
 STAAS & HALSEY LLP Our Docket: 300.1148
 Attention: H. J. Staas
 1201 New York Ave., N.W., Suite 700
 Washington, D.C. 20005
 6. Total number of applications and patents involved: 1
 7. Total fee (37 CFR 3.41)..... (\$ 40.00 per Assignment)
☒ Enclosed
☐ Authorized to be charged to deposit account.
 8. Deposit Account No.: 19-3935 (Any underpayment is authorized to be charged to this Deposit Account)
(Attach duplicate copy of this page if paying by deposit account)
 9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

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 H. J. Staas, Reg. No. 22,010
 Name of Person Signing

Signature

 March 10, 2004
 Date
Total number of pages including cover sheet: 2

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U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter "ASSIGNOR") by

(Insert
ASSIGNEE's
Name(s)
Address(es))

SHINKO ELECTRIC INDUSTRIES CO., LTD.

80, Oshimada-machi, Nagano-shi, Nagano 381-2287, Japan

(hereinafter "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of
Invention)

METHOD OF PRODUCTION OF MULTILAYER CIRCUIT BOARD WITH
BUILT-IN SEMICONDUCTOR CHIP

relating to International Patent Application PCT/JP _____/_____ and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(Insert date
of execution
of application,
if not
concurrent)

(a) executed on _____;
(b) filed on _____,
Serial No. _____/_____;

(_____) is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

1) <u>Masahiro Sunohara</u> (SIGNATURE)	<u>Masahiro Sunohara</u> (TYPE NAME)	<u>February 25, 2004</u> (DATE)
2) <u>Kei Murayama</u> (SIGNATURE)	<u>Kei Murayama</u> (TYPE NAME)	<u>February 25, 2004</u> (DATE)
3) <u>Mitsutoshi Higashi</u> (SIGNATURE)	<u>Mitsutoshi Higashi</u> (TYPE NAME)	<u>February 25, 2004</u> (DATE)
4) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
5) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
6) _____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)